

20V P-Channel Enhancement Mode MOSFET

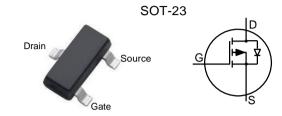
General Features

- Proprietary Advanced Planar Technology
- > Rugged Polysilicon Gate Cell Structure
- > Fast Switching Speed
- > RoHS Compliant
- > Halogen-free Available

BV _{DSS}	R _{DS(ON)} (Typ.)	I_D			
-20V	5.2Ω	-280mA			

Applications

- ➤ High Efficiency SMPS
- > Adaptor/Charger
- ➤ Active PFC



Ordering Information

Part Number	Package	Marking	Remark	
FTZ50P01G5	FTZ50P01G5 SOT-23		Halogen Free	

Absolute Maximum Ratings

T_A=25°C unless otherwise specified

Symbol	Parameter	FTZ50P01G5	Unit
$V_{ m DSS}$	Drain-to-Source Voltage ^[1]	-20	V
I_{D}	Continuous Drain Current	-0.28	A
I_{DM}	Pulsed Drain Current ^[2]	-1.12	A
P _D	Power Dissipation	0.5	W
V _{GS}	Gate-to-Source Voltage	±20	V
T_{L}	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	°C
T _J and T _{STG}	Operating and Storage Temperature Range	-55 to 150	

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to thedevice.

Thermal Characteristics

Symbol	Parameter	FTZ50P01G5	Unit
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	250	K/W



Electrical Characteristics

OFF Characteristics

T_A =25 °C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	-20			V	V_{GS} =0V, I_{D} =-250 μ A
I_{DSS}	Drain-to-Source Leakage Current		-0.23		nA	V _{DS} =-10V,V _{GS} =0V
I_{GSS}	Gate-to-Source Leakage Current		2		nA	V_{GS} =+20V, V_{DS} =0V
			-3			V _{GS} =-20V, V _{DS} =0V

ON Characteristics

T_A =25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
$R_{\mathrm{DS(ON)}}$	Static Drain-to-Source On-Resistance	-	5.2		Ω	V_{GS} =-10V, I_D =-50m $A^{[3]}$
$V_{GS(OFF)}$	Gate-to-Source Cut-off Voltage		-4.38		V	$V_{GD}=0V, I_{D}=-1\mu A$
			-5.24		V	V_{GD} =0V, I_{D} =-250 μ A

Source-Drain Diode Characteristics

T_A=25°C unless otherwise specified

Symbol	Parameter	Min	Тур.	Max.	Units	Test Conditions
V_{SD}	Diode Forward Voltage		1.13		V	I _{SD} =-50mA ^[3] , V _{GS} =0V

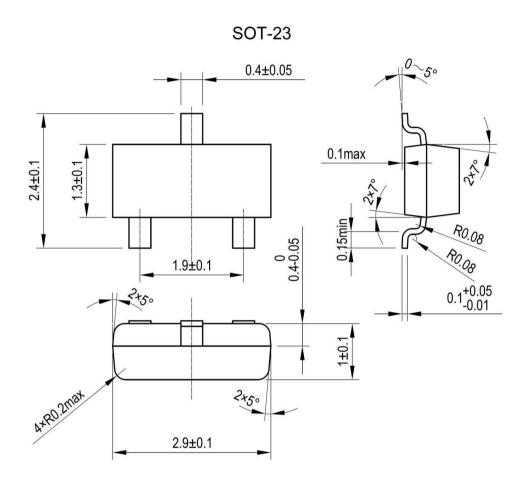
NOTE:

[1] $T_J=+25^{\circ}C$ to $+150^{\circ}C$

[2] Repetitive rating, pulse width limited by maximum junction temperature. [3] Pulse width \leq 380µs; duty cycle \leq 2%.



Package Dimensions





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